ABSTRACT

METHOD FOR MOLECULAR ADHESION BONDING AT LOW PRESSURE

Method for molecular adhesion bonding between at least a first wafer (20) and a second wafer (30) comprising at least a step of mechanical alignment, a step of bringing the two wafers (20, 30) in contact and a step of initiating the propagation of a bonding wave between the two wafers. During the steps of mechanical alignment and bringing the two wafers in contact, the wafers are placed in an environment at a first pressure (P1) greater than or equal to a predetermined pressure threshold value. During the step of initiating the propagation of a bonding wave, the wafers (20, 30) are placed in an environment at a second pressure (P2) less than the said predetermined pressure threshold value.

(Figures 2A and 2I)